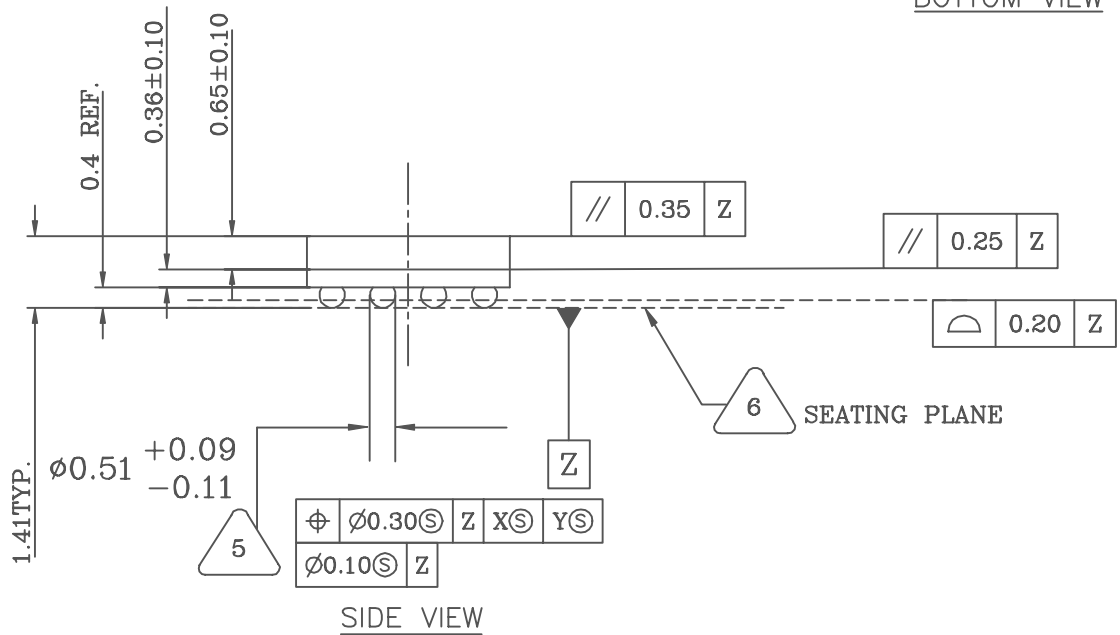
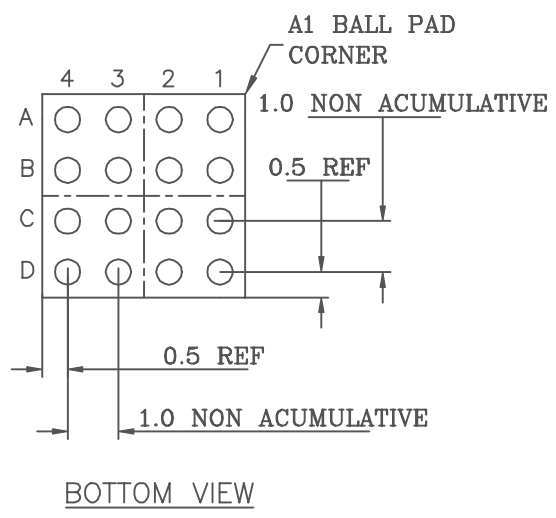
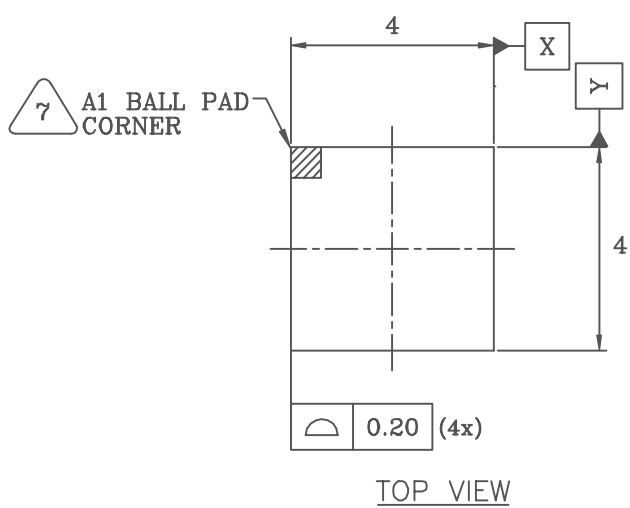


REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	3/00	



NOTES:

- 7. A1 BALL PAD CORNER I.D. IS IDENTIFIED BY LASER MARKED DOT AT THE CORNER.
- 6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
- 4. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 3. SOLDER BALL POSITION DESIGNATION PER JESD 95-1, SPP-010.
- 2. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
- 1. ALL DIMENSIONS ARE IN MILLIMETERS

SIGNATURE		DATE							
DOC. CONTROL:									
ENGR. MGR:				TITLE MARKETING OUTLINE - 16L CHIP SCALE BGA (4X4) 1.0MM PITCH, 1.41 THICK, 2 LAYER					
MFG. ENGR:				SIZE		PART NO.		REV.	
CHECKED BY:		3/00		A		56-G6005-001		A	
DRAWN BY:		3/00		SCALE		SHEET		1 of 1	
DO NOT SCALE DRAWING				N/A					